

Silicon wafer cutting fluid DK-760M

【Performance and use】

Silicon wafer cutting fluid DK-760M is suitable for various machining processes of semiconductor materials such as monocrystalline silicon, polycrystalline silicon, wafers, and ceramics, including milling, rolling, coarse grinding, fine grinding, edge grinding, and chamfering. It offers strong lubrication and cleaning penetration, effectively enhancing processing efficiency and being a reliable aid in your machining operations.

【Main technical parameters】

item	Technical indicators	Test method
External view	Yellowish brown liquid	GB6144-85
pH value	9.3± 0.2	GB6144-85
Defoaming (ml)	2 or less	GB6144-85
Specific weight (g/ml)	1.0 ± 0.05	Pycnometer method
Surface tension (dyn/cm)	30 or less	GB6144-85
Storage stability	conjunctive	GB6144-85
corrosiveness	Grade A cast iron	GB6144-85
Rust resistance	Grade A cast iron	GB6144-85

【Product advantage】

- has high grinding speed, excellent lubricity and self-sharpening performance.
- Excellent wettability and cleaning, powder can quickly settle.
- No odor, no foam, no corrosion machine.

【Instruction】

1. The working liquid is diluted with 10-20 times tap water or deionized water.
2. In the course of use, the clean working liquid can be replenished at a concentration of 3-5%.
3. Avoid mixing with other oils.

【Packaging】

18L/ barrel, 25L/ barrel, 200L/ barrel.

【Note】

1. This product should not be mixed with other emulsions, semi-synthetic liquids, and fully synthetic liquids, because even if the system contains a small amount of rotten residual liquid, it will affect the use effect of the new liquid.

2.the production batch is not the same, the cutting fluid may have color differences, does not affect the normal use.